

SOT2199-1

HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals,
0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

9 July 2025

Package information



1 Package summary

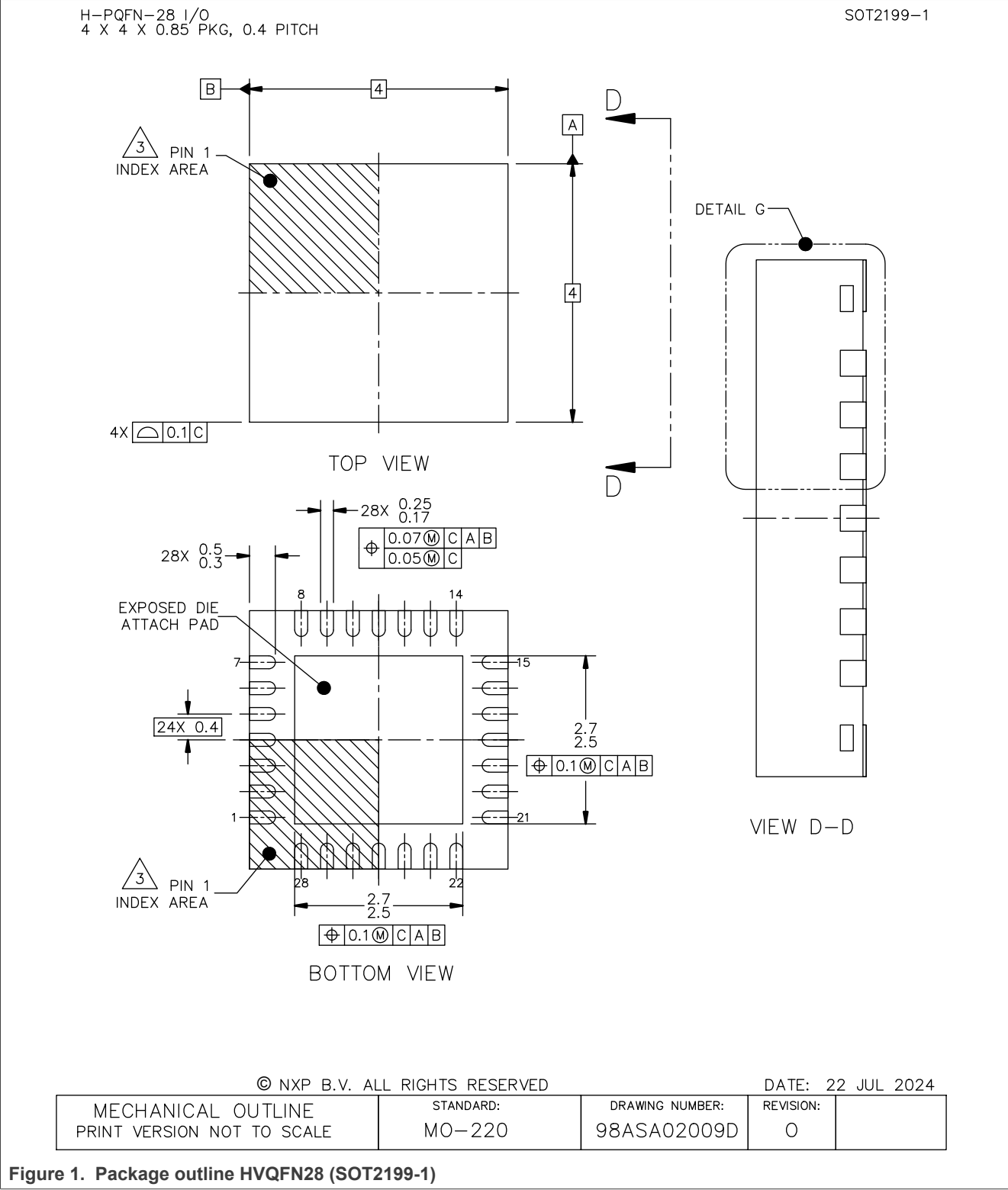
Terminal position code	Q (quad)
Package type descriptive code	HVQFN28
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-07-2025
Manufacturer package code	98ASA02009D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	28	-	

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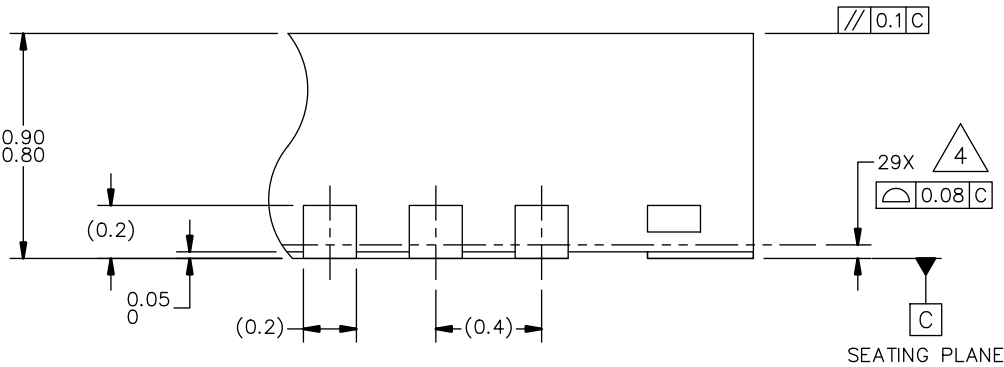
2 Package outline



HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-28 I/O
4 X 4 X 0.85 PKG, 0.4 PITCH

SOT2199-1



DETAIL G
VIEW ROTATED 90° CW

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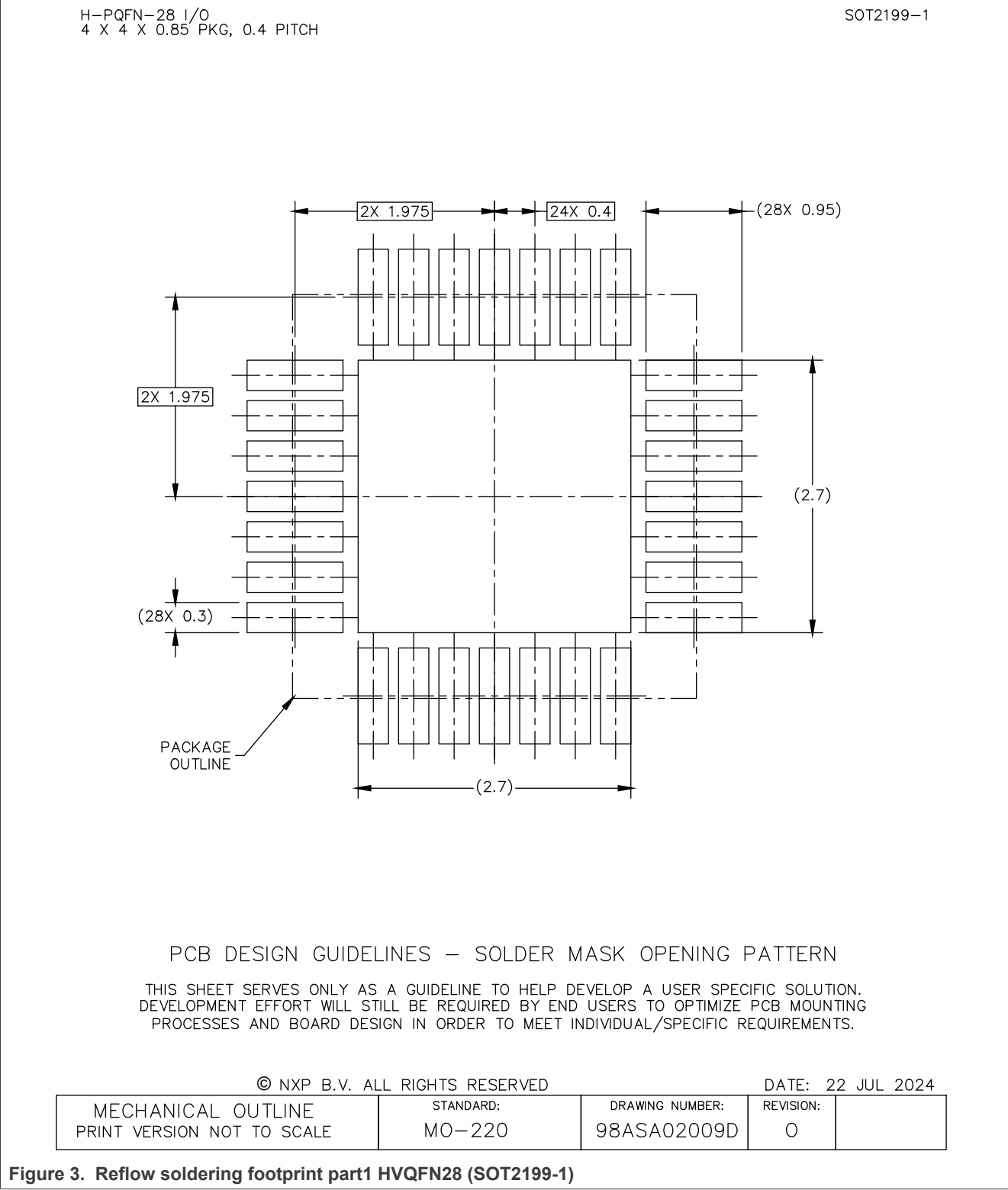
DATE: 22 JUL 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA02009D	REVISION: O	
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Figure 2. Package outline detail G of HVQFN28 (SOT2199-1)

HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

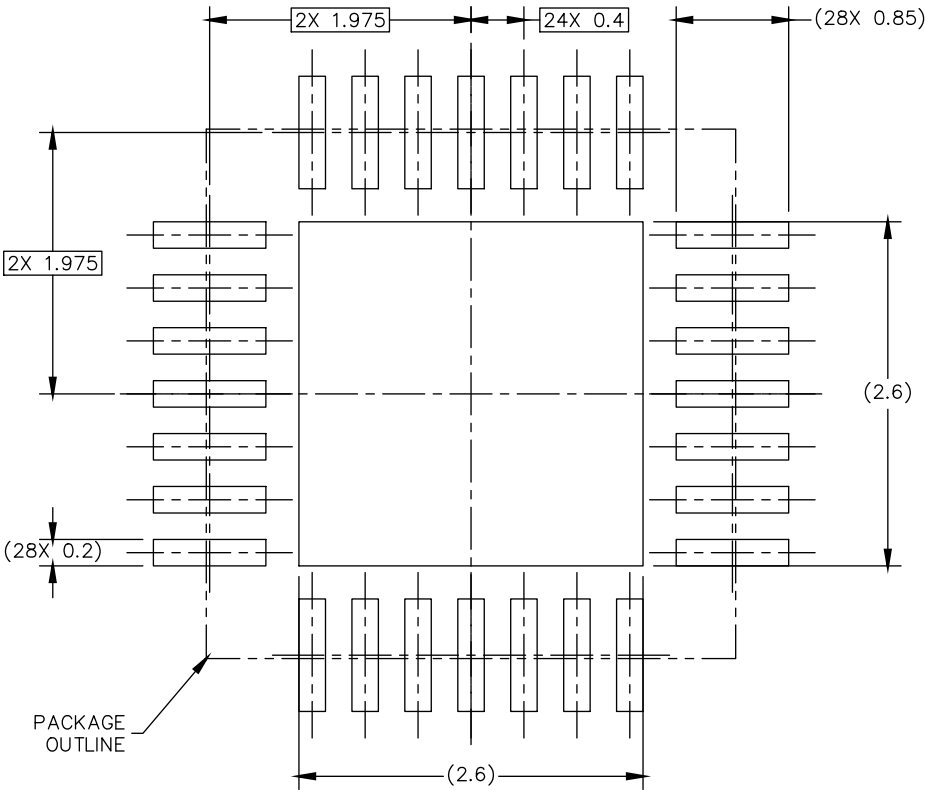
3 Soldering



HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-28 I/O
4 X 4 X 0.85 PKG, 0.4 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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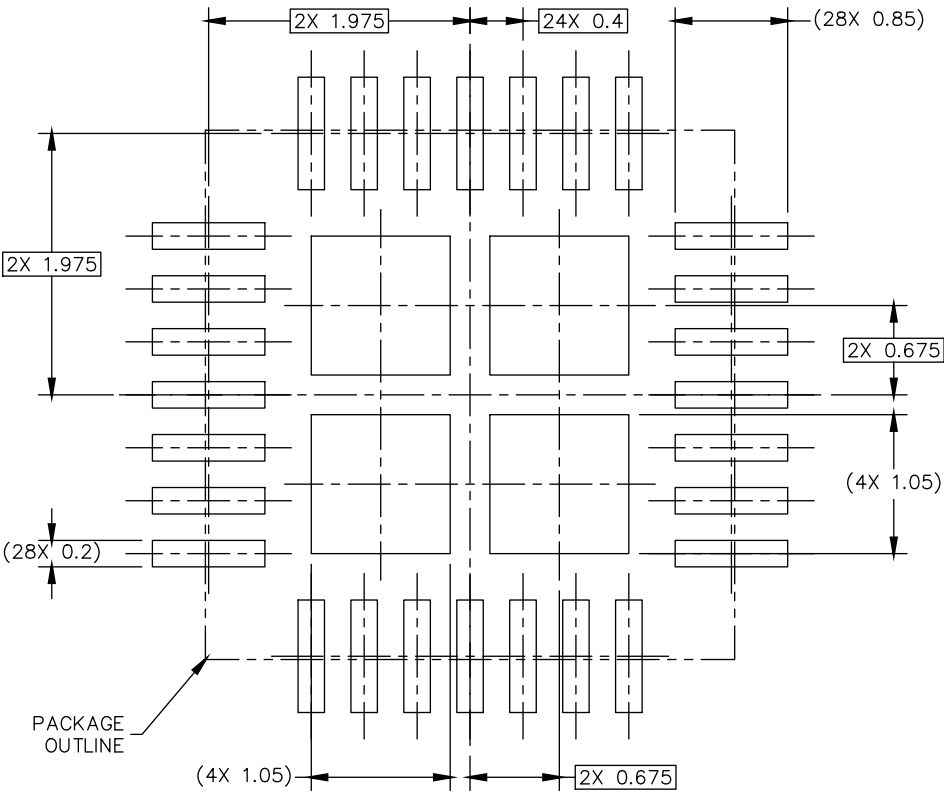
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Figure 4. Reflow soldering footprint part2 HVQFN28 (SOT2199-1)

HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-28 I/O
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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 HVQFN28 (SOT2199-1)

HVQFN28, thermal enhanced very thin quad flatpack; no leads, 28 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-28 I/O
4 X 4 X 0.85 PKG, 0.4 PITCH

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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
- 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN28 (SOT2199-1)

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4 Legal information

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